

WHAT IS CLAIMED IS:

1. A semiconductor chip assembly of the type including a semiconductor chip having a plurality of surfaces and having contacts on at least one of said surfaces and a flexible sheetlike element having terminals thereon electrically connected to said contacts, characterized in that said sheetlike element and at least some of said terminals overlie one said surface of said chip, said terminals are movable with respect to said chip and the assembly includes resilient means for permitting movement of said terminals toward said chip.

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a6 >*

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*Add  
B6*

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